



Material Content Data Sheet



Sales Product Name	TLE9271QX V33			Issued	31. January 2019			
MA#	MA004737218							
Package	PG-VQFN-48-31			Weight*	129.76 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.989	3.07	3.07	30743	30743
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11045	
wire	non noble metal	copper	7440-50-8	58.193	44.86	46.03	448484	460219
	non noble metal	copper	7440-50-8	0.584	0.45	0.45	4500	4500
	encapsulation	organic material	carbon black	1333-86-4	0.184	0.14		1415
	plastics	epoxy resin	-	7.771	5.99		59886	
		inorganic material	silicondioxide	60676-86-0	53.231	41.02	47.15	410245
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20010	20010
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4731	4731
glue	plastics	epoxy resin	-	0.246	0.19		1898	
		noble metal	silver	7440-22-4	0.824	0.64	0.83	6353
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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